IPC ASSOCIATION ELECTRONIC		Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved und international and Pan-American copyright conventions.			ler both	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowe level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
1752-21.1						Form Type Distribute					als and Mfg Information				
Supplier	r Informa	tion													
Company name* Company unique ID				ique ID		Unique ID Authority					Response Date*				
onsemi												2024-05-19			
Contact Name				Title - Contact				Phone - Contact*				Email - Contact*			
Product-Env-Stewards				Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
Authorized Representative*				Title - Representative				Phone - Representative*			Email - Representative*				
Product-Env-Stewards				Product Enviro Compliance				NA				Product-Env-Stewards@onsemi.com			
	Requester Item Number Mfr Item		Mfr Item	Number Mfr Item Name				Effective Da	Date Version Manufacturing Site		Weigh	ıt*	UOM	Unit Type	
			MUR410	0E				2024-05-19				1334.6	52	mg	Each
Manufa	cturing P	roccess Information	n						·						
	Terminal Pl	lating / Grid Array Materi	ial To	erminal Base	Alloy J-S	STD-020 MS	L Rating	Peak Pro	cess Body	Tempera	ture Max Time at Peak	Temperature	Numbe	r of Reflow Cyc	les
			C	U Alloy						С	30	seconds	3		
Comments	3														
or more i	information	regarding material con	nposition p	olease refer to	page 3										

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its paragraph. If the Company and the Supplier have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard											
RoHS Declaration * 4 - Item(s	) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

<b>Homogeneous Material</b>	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	6.67	mg	Supplier	Silicon (Si)	7440-21-3		6.67	mg
Die Attach Solder	46.69	mg	Supplier	Silver (Ag)	7440-22-4		1.1673	mg
			A	Lead (Pb)	7439-92-1	7a	43.1882	mg
			Supplier	Tin (Sn)	7440-31-5		2.3345	mg
Lead Frame	731.48	mg	Supplier	Copper (Cu)	7440-50-8		731.48	mg
Mold Compound-Black	543.33	mg		Epoxy resin	proprietary data		38.0331	mg
			Supplier	Phenolic Resin	Proprietary Data		38.0331	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		81.4995	mg
			Supplier	Carbon Black (C)	1333-86-4		2.7167	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		383.0476	mg
Plating	6.45	mg	Supplier	Tin (Sn)	7440-31-5		6.45	mg